

Product Advisory (PA)

Subject: Change of the standard interior label of Renesas Electronics

Publication Date: December 1, 2022

Effective Date: Refer to Appendix A to D

Revision Description:

Initial Release

Description of Change:

Renesas Electronics will update and streamline the standard interior labels in shipments for all products in conjunction with our systems integration plan.

Kindly refer to Appendix A to D for comparison on the current and new standard labels.

Materials related to 2D barcode specifications is available upon request.

Affected Product List:

All products, including legacy Intersil, IDT, Dialog and Renesas except custom-labeled products.

Reason for Change:

To integrate company-wide standard labels through the integration of SCM systems, including logistic systems.

Impact on Fit, Form, Function, Quality & Reliability:

This change will have no impact on the form, fit, function, quality, reliability and environmental compliance of the devices.

Qualification Status: Not applicable

Sample Availability Date: Not applicable

Device Material Declaration: Not applicable

Questions or requests pertaining to this change notice, including additional data, must be sent to Renesas within 30 days of the publication date.

APPENDIX A: LEGACY INTERSIL PRODUCTS

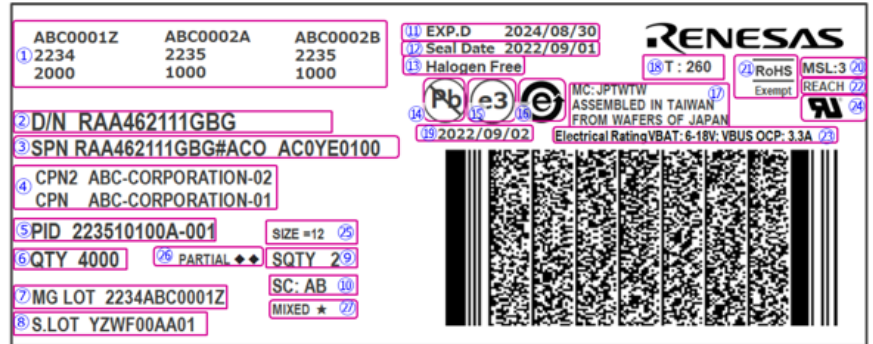
Effective Date: August 1, 2023

Product Identification:

The new standard label after the change is as follows.

Table 3 : Label Display Item

Label Display Item
① Lot Combine Information
② D/N (Device Name)
③ SPN (SAP Parts Name)
④ CPN / CPN2 (Customer Parts No.)
⑤ PID (Pack ID)
⑥ QTY
⑦ MG LOT (Manufacturing Lot No.)
⑧ S.Lot (Shipping Batch Lot)
⑨ SQTY (Wafers Q'ty)
⑩ OSAT Code
⑪ Expiry Date
⑫ Seal Date
⑬ Halogen Free
⑭ Pb-Free Logo Mark
⑮ Pb-Free with Detail Rank Information
⑯ China RoHS (Logo Mark or "Blank")
⑰ Country of Origin
⑱ PCB On Board Reflow Rank (Peak Temp)
⑲ Labeling Date
⑳ Condition after opening (MSL Rank)
㉑ RoHS Exempt (RoHS or RoHS Exempt)
㉒ REACH Certified (REACH or "Blank")
㉓ UL Certified
㉔ UL Rank
㉕ Wafer Size
㉖ Partial Lot Sign
㉗ Mix Lot Sign



Comparison before and after change for legacy INTERSIL products

Gap Points Current and New / Ex-ISL

The diagram illustrates the transition from legacy labels to new labels. On the left, three legacy labels are shown for 'For Finished Goods' and 'For Wafer Sales'. On the right, two new labels are shown, also for 'For Wafer Sales'. Dimensions are indicated: 42mm for the top section, 10mm for the middle section, and 32mm for the bottom section. A total width of 100mm is also shown. A yellow arrow points from the legacy labels to the new labels.

Gap Points

- Added Items
 - PID (Traceability Control)
 - S.LOT (Traceability Control) For Renesas Internal Use
 - Add RoHS / RoHS Exempt (Display RoHS or RoHS Exempt)
 - Add China RoHS (Display China RoHS Certified)
- Design Change Items
 - SPN (Orderable Parts No.)
 - CPN/CPN2 (Customer Parts No.)
 - Lot Combine Information
 - Country of Origin (Manufacturing Country Info.)
 - PCB On Board Reflow Rank (Peak Temperature)
 - MG LOT (Manufacturing Lot No.)

For additional information regarding this notice, please contact your regional change coordinator (below)

Americas: PCN-US@Renesas.COM	Europe: PCN-EU@Renesas.COM	Japan: PCN-JP@Renesas.COM	Asia Pac: PCN-APAC@Renesas.COM
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APPENDIX B: LEGACY IDT PRODUCTS

Effective Date: August 1, 2023

Product Identification:

The new standard label after the change is as follows.

Table 3 : Label Display Item

Label Display Item
① Lot Combine Information
② D/N (Device Name)
③ SPN (SAP Parts Name)
④ CPN / CPN2 (Customer Parts No.)
⑤ PID (Pack ID)
⑥ QTY
⑦ MG LOT (Manufacturing Lot No.)
⑧ S.Lot (Shipping Batch Lot)
⑨ SQTY (Wafers Q'ty)
⑩ OSAT Code
⑪ Expiry Date
⑫ Seal Date
⑬ Halogen Free
⑭ Pb-Free Logo Mark
⑮ Pb-Free with Detail Rank Information
⑯ China RoHS (Logo Mark or "Blank")
⑰ Country of Origin
⑱ PCB On Board Reflow Rank (Peak Temp)
⑲ Labeling Date
⑳ Condition after opening (MSL Rank)
㉑ RoHS Exempt (RoHS or RoHS Exempt)
㉒ REACH Certified (REACH or "Blank")
㉓ UL Certified
㉔ UL Rank
㉕ Wafer Size
㉖ Partial Lot Sign
㉗ Mix Lot Sign



Comparison before and after change for legacy IDT products

Gap Points Current and New / Ex-IDT

For Finished Goods

For Wafer Sales

42mm

100mm

10mm

32mm

For Wafer Sales

Gap Points

- Added Items
 - PID (Traceability Control)
 - S.LOT (Traceability Control)
 - For Renesas Internal Use
- Design Change Items
 - SPN (Orderable Parts No.)
 - Lot Combine Information
 - MG LOT (Manufacturing Lot No.)
 - Pb-Free's Logo Mark
 - Country of Origin (Manufacturing Country Info.)
 - PCB On Board Reflow Rank (Peak Temperature)

For additional information regarding this notice, please contact Idt-pcn@lm.renesas.com.

APPENDIX C: LEGACY DIALOG PRODUCTS

Effective Date: August 1, 2023

Product Identification:

The new standard label after the change is as follows.

Table 3 : Label Display Item

Label Display Item
① Lot Combine Information
② D/N (Device Name)
③ SPN (SAP Parts Name)
④ CPN / CPN2 (Customer Parts No.)
⑤ PID (Pack ID)
⑥ QTY
⑦ MG LOT (Manufacturing Lot No.)
⑧ S.Lot (Shipping Batch Lot)
⑨ SQTY (Wafers Q'ty)
⑩ OSAT Code
⑪ Expiry Date
⑫ Seal Date
⑬ Halogen Free
⑭ Pb-Free Logo Mark
⑮ Pb-Free with Detail Rank Information
⑯ China RoHS (Logo Mark or "Blank")
⑰ Country of Origin
⑱ PCB On Board Reflow Rank (Peak Temp)
⑲ Labeling Date
⑳ Condition after opening (MSL Rank)
㉑ RoHS Exempt (RoHS or RoHS Exempt)
㉒ REACH Certified (REACH or "Blank")
㉓ UL Certified
㉔ UL Rank
㉕ Wafer Size
㉖ Partial Lot Sign
㉗ Mix Lot Sign



Comparison before and after change for legacy DIALOG products

Gap Points Current and New / Ex-DLG

For Finished Goods

For Wafer Sales

Gap Points

Added Items

- PID (Traceability Control)
- EXP. Date (Traceability Control) For Renesas Internal Use
- S.LOT (Traceability Control) For Renesas Internal Use

Design Change Items

- Renesas Logo Mark
- SPN (Orderable Parts No.)
- CPN/CPN2 (Customer Parts No.)
- MG LOT (Manufacturing Lot No.)
- Lot Combine Information
- Country of Origin (Manufacturing Country Info.)
- PCB On Board Reflow Rank (Peak Temperature)
- SC (Test Supplier Code)

For additional information regarding this notice, please contact your Renesas sales representative.

APPENDIX D: LEGACY RENESAS PRODUCTS

Effective Date: April 1, 2024

Product Identification:

The new standard label after the change is as follows.

Table 3 : Label Display Item

Label Display Item
① Lot Combine Information
② D/N (Device Name)
③ SPN (SAP Parts Name)
④ CPN / CPN2 (Customer Parts No.)
⑤ PID (Pack ID)
⑥ QTY
⑦ MG LOT (Manufacturing Lot No.)
⑧ S.Lot (Shipping Batch Lot)
⑨ SQTY (Wafers Q'ty)
⑩ OSAT Code
⑪ Expiry Date
⑫ Seal Date
⑬ Halogen Free
⑭ Pb-Free Logo Mark
⑮ Pb-Free with Detail Rank Information
⑯ China RoHS (Logo Mark or "Blank")
⑰ Country of Origin
⑱ PCB On Board Reflow Rank (Peak Temp)
⑲ Labeling Date
⑳ Condition after opening (MSL Rank)
㉑ RoHS Exempt (RoHS or RoHS Exempt)
㉒ REACH Certified (REACH or "Blank")
㉓ UL Certified
㉔ UL Rank
㉕ Wafer Size
㉖ Partial Lot Sign
㉗ Mix Lot Sign



Comparison before and after change for legacy RENESAS products

Gap Points Current and New / Renesas Japan (REL)



Gap Points

- Design Change Items
 - Pb-Free's Logo Mark
 - PCB On Board Reflow Rank (Peak Temperature)
 - Customer Parts No. (Display Name Change)
 - PN/PN2 => CPN/CPN2
 - MG LOT (Display Name Change)
 - T/C => MG LOT
 - PCN (Deleted Item)

For additional information regarding this notice, please contact your Renesas sales representative.